

4

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D

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C

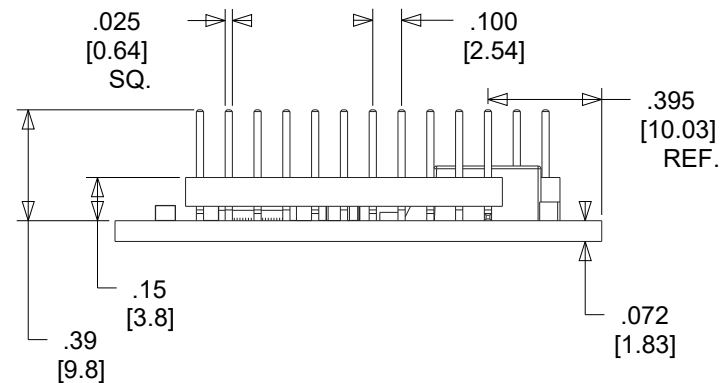
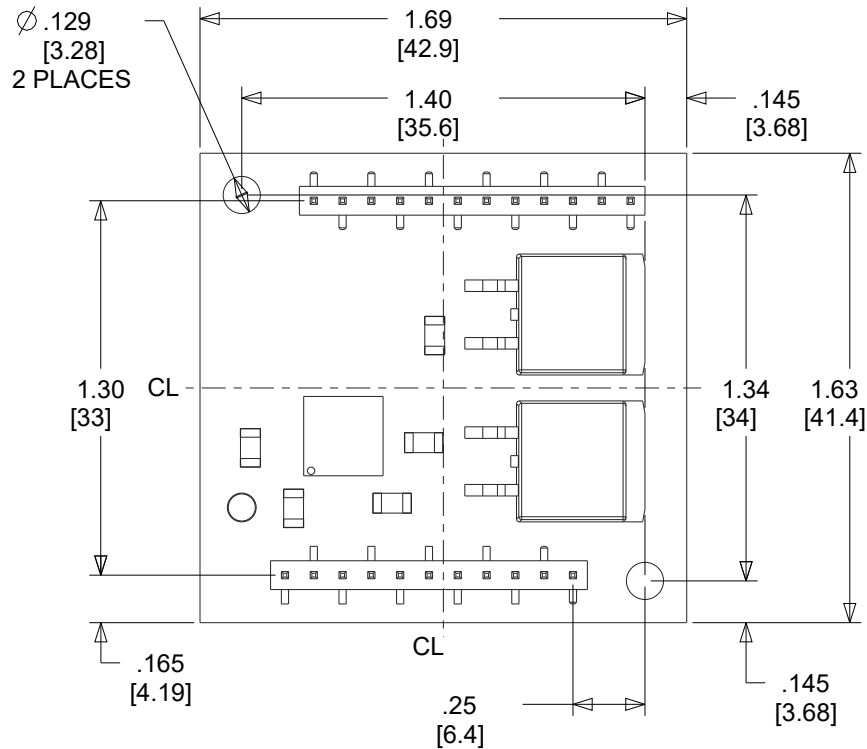
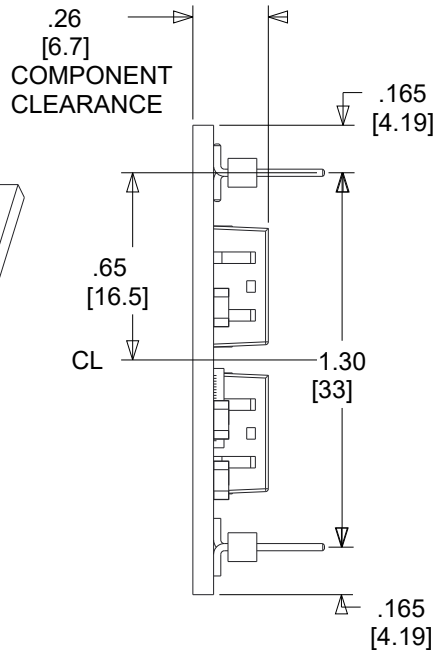
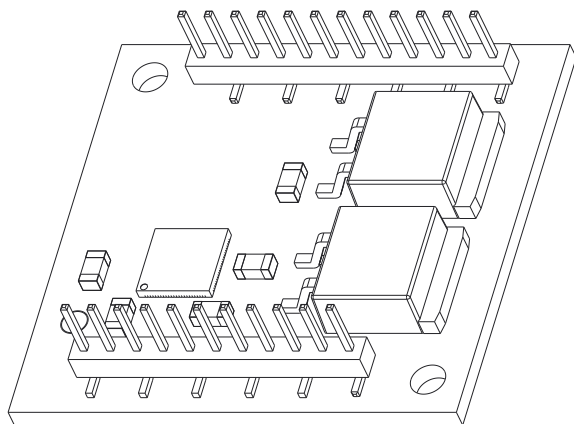
C

B

B


A

A



NOTES:

1. Dimensions are in inches [mm].
2. Scale: 1.5x
3. Recommended PCB hole diameter for pins: 0.050[1.27].
4. 2oz. copper over 600V dielectric over aluminum substrate.
5. Tin over nickel plated phospher bronze pins.
6. It is not recommended that mounting of the package rely on the pins for mechanical support.
7. Use #4 or equivalent screws to mount to heat sink.
8. Package Weight: 13 grams.

TOLERANCES - UNLESS OTHERWISE SPECIFIED					TITLE: MODULAR 23-PIN DIP 1.3" SPACING		MODEL: KL	
.XX = +/- .05" [1.27] .XXX = +/- .005" [0.127] ANG. = +/- 2 DEGREES					SUBJECT: PACKAGE OUTLINE		ENGINEER: AA	
		DCA: 19051		SH. 1		OF 1		
		FILENAME: KL		REV: C		DATE: 11FEB19		

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